DS90UH981-Q1 支持 HDCP 的 4K DSI 转 FPD-Link IV 桥接串行器

1 特性

- 单端口或双端口 MIPI DSI 接收器
  - 符合 D-PHY v1.2 和 DSI v1.3.1 标准
  - 紧凑型 16/18/24/30 位 RGB 和 16 位 YCbCr
  - 松散型 18 位 RGB 和 20 位 4:2:2
  - 每个 D-PHY 端口 1 个时钟通道和 1-4 个可配置数据通道
  - 高达 2.5Gbps/通道（带偏斜校准）
  - 支持数据通道交换和极性反转
  - 支持突发和非突发模式
  - 超级帧解包功能
  - 适用于 4K (60Hz) 视频分辨率
- FPD-Link IV 接口
  - 支持每通道 10.8/6.75/3.375Gbps；双通道高达 21.6Gbps
  - 同轴/STP 互连支持
  - 端口拆分，以启用 Y 型电缆接口
- 超低延迟控制通道
  - 两个高达 1MHz 的 I2C（本地总线访问高达 3.4MHz）
  - 高速 GPIO
- 向后兼容，
  - 具有片上密钥的集成 HDCP v1.4
  - 720P 92x 和 1080P/2K 94x 产品系列
  - ADAS 936、954、960、962、9702、9722 解串器
- 安全和诊断
  - 电压和温度监测
  - 线路故障检测
  - BIST 和图形生成
  - CRC 和错误诊断
  - 用于防伪认证的唯一 ID
  - 控制位上的 ECC
- 高级链路稳定性和 EMC 控制
  - 数据换序
  - 展频时钟生成 (SSCG)
- 低功耗操作
  - 1.8V 和 1.1V 双电源供电
- 符合面向汽车应用的 AEC-Q100 标准
  - AEC-Q100 等级 2：-40°C 至 +105°C
  - 64 引脚 QFN 可湿性侧面 9mm x 9mm
  - 符合 ISO 10605 和 IEC 61000-4-2 ESD 标准

2 应用

- 汽车显示器：
  - 中央信息显示屏 (CID)
  - 后座娱乐系统 (RSE)
  - 数字仪表组
  - 音响主机和 HMI 模块
  - 抬头显示 (HUD)
  - 后视显示器和侧后视镜显示器

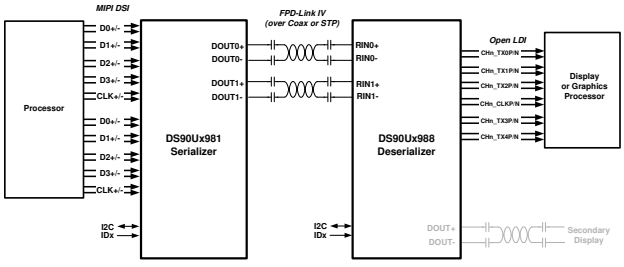
3 说明

DS90UH981-Q1 是一款 MIPI DSI 转 FPD-Link III/IV 桥接器件。该芯片组与 FPD-Link IV 解串器配合使用，可通过低成本 50Ω 同轴电缆或 STP 电缆提供高速串行化接口。DS90UH981-Q1 是一款符合 D-PHY v1.2 标准的器件，可对 MIPI DSI 输入进行串行化处理，支持包括 4K 在内的视频分辨率以及 30 位色深。FPD-Link IV 接口支持通过单通道或双通道进行视频和音频数据传输和全双工控制，包括 I2C 和 GPIO 数据。通过两个 FPD-Link IV 通道实现视频数据和控制的整合可减小互连线尺寸和重量，并简化系统设计。通过使用低电压差分信号、数据换序、SSCG 和随机生成更大限度减少了 EMI。在向后兼容 模式下，该器件通过单/双链路支持高达 720p 和 1080p 的分辨率以及 24 位色深，并且在与支持 HDCP 的解串器配合使用时支持 HDCP v1.4。在 ADAS 兼容模式下，该器件可与 936、95x、96x 和 97x 解串器互操作，支持高达 8MP+/40fps 的分辨率。

封装信息

器件型号	封装 (1)	封装尺寸(2)
DS90UH981-Q1	RTD（VQFNP，64）	9.00mm × 9.00mm

(1) 如需了解所有可用封装，请参阅节 6。
(2) 封装尺寸（长 × 宽）为标称值，并包括引脚（如适用）。



简化版应用示意图

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4 Device and Documentation Support

4.1 Documentation Support

4.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, *Soldering Specifications* application note
- Texas Instruments, *Semiconductor and IC Package Thermal Metrics* application note
- Texas Instruments, *Leadless Leadframe Package (LLP)* application note
- Texas Instruments, *LVDS Owner's Manual*
- Texas Instruments, *I2C Communication Over FPD-Link III with Bidirectional Control Channel* application note
- Texas Instruments, *Exploring the Internal Test Pattern Generation Feature of 720p FPD-Link III Devices* application note
- Texas Instruments, *I2C Bus Pullup Resistor Calculation* application note
- Texas Instruments FPD-Link Learning Center, *FPD-Link Fundamental Material* video series
- Texas Instruments, *Ten tips for successfully designing with automotive EMC/EMI requirements*
- Texas Instruments, *Serial Line-Fault Detection* (Contact TI)

4.2 Trademarks

所有商标均为其各自所有者的财产。

4.3 静电放电警告

静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

4.4 术语表

TI 术语表　　本术语表列出并解释了术语、首字母缩略词和定义。

5 Revision History

注：以前版本的页码可能与当前版本的页码不同

DATE	REVISION	NOTES
February 2024	*	Initial Release

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6 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DS90UH981RTDRQ1	Active	Production	VQFN (RTD) | 64	2000 | LARGE T&R	Yes	NIPDAUAG	Level-3-260C-168 HR	-40 to 105	UH981
DS90UH981RTDRQ1.A	Active	Production	VQFN (RTD) | 64	2000 | LARGE T&R	Yes	NIPDAUAG	Level-3-260C-168 HR	-40 to 105	UH981
DS90UH981RTDTQ1	Active	Production	VQFN (RTD) | 64	250 | SMALL T&R	Yes	NIPDAUAG	Level-3-260C-168 HR	-40 to 105	UH981
DS90UH981RTDTQ1.A	Active	Production	VQFN (RTD) | 64	250 | SMALL T&R	Yes	NIPDAUAG	Level-3-260C-168 HR	-40 to 105	UH981

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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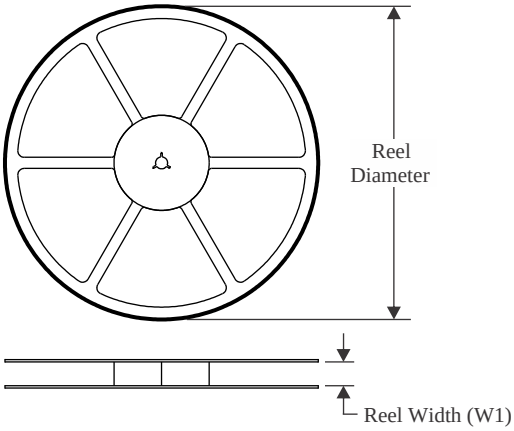
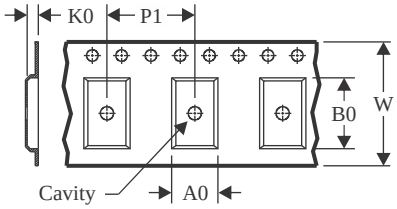
TAPE AND REEL INFORMATION

REEL DIMENSIONS

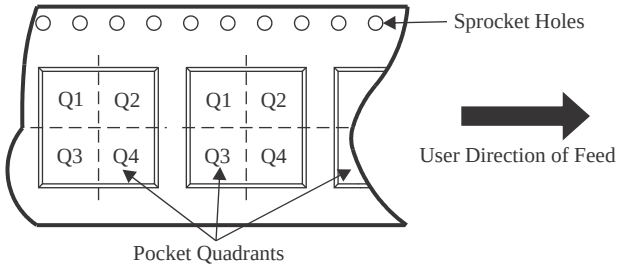


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

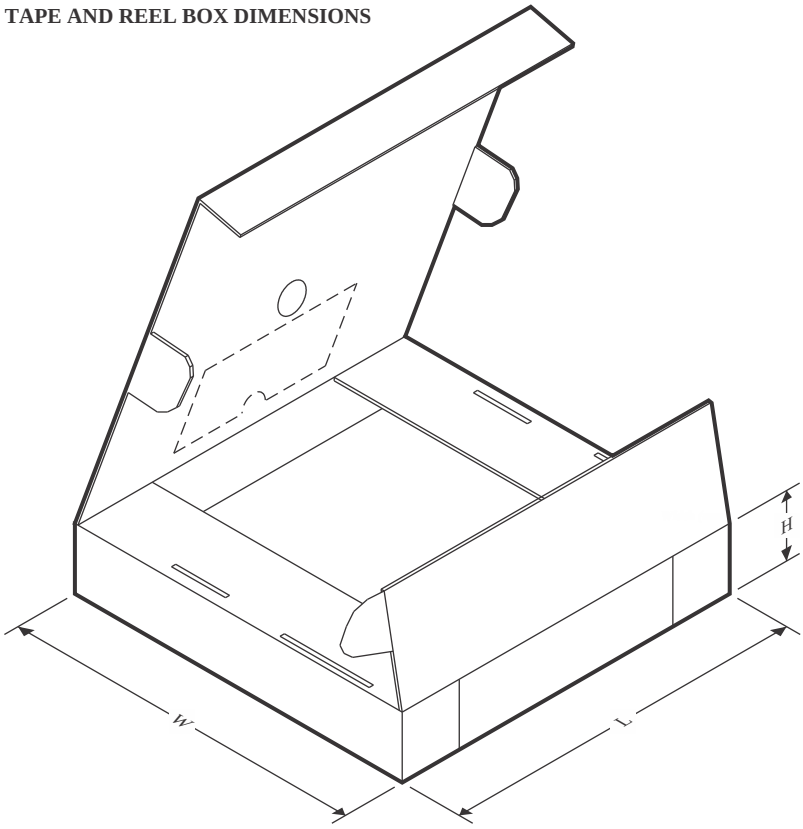
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DS90UH981RTDRQ1	VQFN	RTD	64	2000	330.0	16.4	9.3	9.3	1.1	12.0	16.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

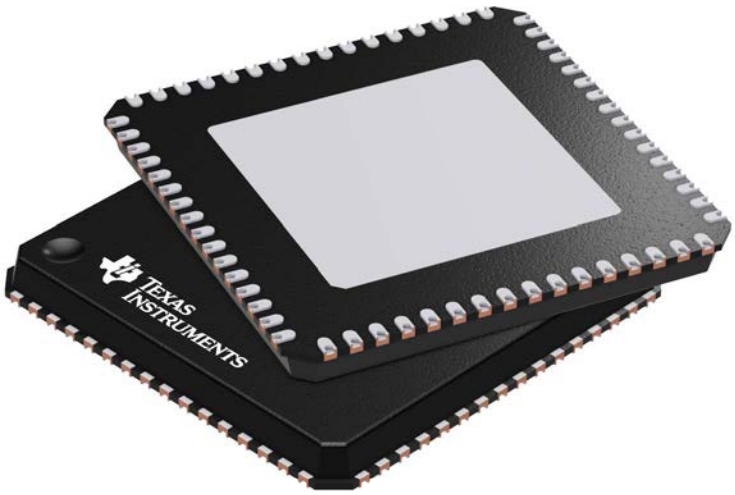
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DS90UH981RTDRQ1	VQFN	RTD	64	2000	367.0	367.0	38.0

GENERIC PACKAGE VIEW

RTD 64

VQFNP - 0.9 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

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最后更新日期：2025 年 10 月